

Smart Configurator for RZ V2.1.0

Release Note

Introduction

Thank you for using the Smart Configurator for RZ.

This document describes the restrictions and points for caution. Read this document before using the product.

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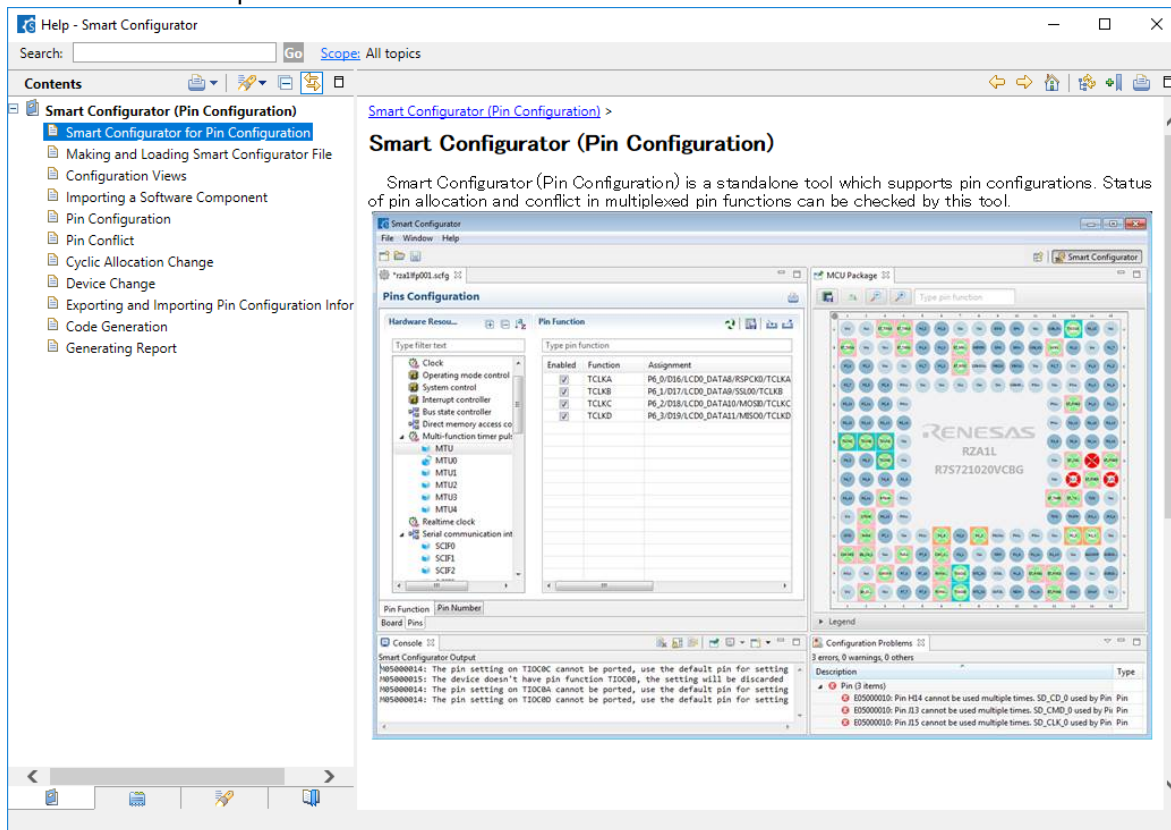
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1. Introduction

The Smart Configurator for RZ is a standalone GUI-based tool for setting the assignments of pin functions to pins in the design of hardware specifications. The assignments of pins can be set up from a GUI, which also checks and offers solutions for cases of contention for the same pins by multiplexed functions.

Please refer to "Help Contents" about how to use.



1.1 System Requirements

The operating environment is as follows:

1.1.1 For Windows 64-bit version

- System: x64 based processor, 2 GHz or faster, CPU has dual cores or more
 - Windows® 11 (64-bit version)
- Memory capacity: We recommend 8 GB or more. At least 4 GB.
- Hard disk capacity: At least 2 GB of free space.
- Display: 1024 x 768 or higher resolution, 65,536 or more colors.
- All other necessary software environments in addition to Windows OS
 - Java Runtime Environment

1.1.2 For Linux

- System: x64 based processor, 2 GHz or faster, CPU has dual cores or more
 - Ubuntu 22.04 LTS Desktop (64-bit version)
 - Ubuntu 24.04 LTS Desktop (64-bit version)
- Memory capacity: We recommend 2 GB or more.
- Hard disk capacity: At least 2 GB of free space.

1.1.3 For Mac OS

- System: 1.8 GHz or faster 64-bit processor. Dual-core or better recommended. Apple Silicon (arm64) processors are only supported.
 - Mac OS 15 (Sequoia)
 - Mac OS 26 (Tahoe)
- Memory capacity: 4 GB of RAM; 8 GB of RAM recommended.
- Hard disk capacity: At least 2 GB of free space.
- Display: 1280 x 800 or higher resolution.

2. Support List

2.1 Supported Devices List

Below is a list of devices supported by the Smart Configurator for RZ V2.1.0.

Table 1. Supported Devices

| Device group | Pin | Device name |
|---------------|------------------|-------------------------------------------------|
| RZ/A1L group | 176pin | R7S721020VCBG R7S721020VCFP R7S721020VLFP |
| | 208pin | R7S721021VCFP R7S721021VLFP |
| RZ/A1LU group | 176pin | R7S721030VCBG R7S721030VCFP R7S721030VLFP |
| | 208pin | R7S721031VCFP R7S721031VLFP |
| | 233pin | R7S721031VCBG R7S722031VLBG |
| RZ/A1LC group | 176pin | R7S721034VCBG |
| RZ/A1H group | 256pin | R7S721000VCBG R7S721000VCFP R7S721000VLFP |
| | 324pin | R7S721001VCBG R7S721001VLBG |
| RZ/A1M group | 256pin | R7S721010VCBG R7S721010VCFP R7S721010VLFP |
| | 324pin | R7S721011VCBG R7S721011VLBG |
| RZ/G1M group | 831pin | R8A77430 |
| RZ/G1E group | 501pin | R8A77450 |
| RZ/G1H group | 831pin | R8A77420 |
| RZ/G1N group | 831pin | R8A77440 |
| RZ/G2E group | 552pin | R8A774C0 |
| RZ/G2M group | 1022pin | R8A774A0 |
| RZ/G2N group | 1022pin | R8A774B0 |
| RZ/G2H group | 1022pin | R8A774E0 |
| RZ/G2L group | 456pin 551pin | R9A07G044L (15mm) R9A07G044L (21mm) |
| RZ/G2LC group | 361pin | R9A07G044LC |
| RZ/V2L group | 456pin 551pin | R9A07G054L (15mm) R9A07G054L (21mm) |
| RZ/G2UL group | 361pin | R9A07G043U |
| RZ/Five group | 266pin 361pin | R9A07G043F00GBG R9A07G043F01GBG |

| Device group | Pin | Device name |
|--------------|------------------|----------------------------------------|
| RZ/G3S group | 359pin 361pin | R9A08G045S (14mm) R9A08G045S (13mm) |
| RZ/V2H group | 1369pin | R9A09G057H |
| RZ/N2H group | 576pin | R9A09G087M (RZ/N2H) |
| RZ/T2H group | 729pin | R9A09G077M (RZ/T2H) |
| RZ/V2N group | 1368pin | R9A09G056N (RZ/V2N) |
| RZ/G3E group | 529pin 625pin | R9A09G047E (15mm) R9A09G047E (21mm) |

Table 2. Supported Devices for RZ Tools

| No. | Target device | RZ Tools | | |
|-----|---------------|------------------|-----------------|-----------|
| | | DDR Configurator | Install Utility | DDR Tools |
| 1 | RZ/G2L | ✓ | ✓ | ✓ |
| 2 | RZ/G3S | ✓ | ✓ | ✓ |
| 3 | RZ/G3E | ✓ | ✓ | ✓ |

✓ :Applicable, -:Not Applicable

3. Changes

3.1 New Support

3.1.1 Added new device support for DDR Configurator

DDR Configurator now supports new devices from the RZ/G device group.

[Target]

- RZ/G2L
- RZ/G3E

3.1.2 Added new device support for Install Utility

Install Utility now supports new devices from the RZ/G device group.

[Target]

- RZ/G3E

3.1.3 Added new device support for DDR Tools

DDR Tools now supports new devices from the RZ/G device group.

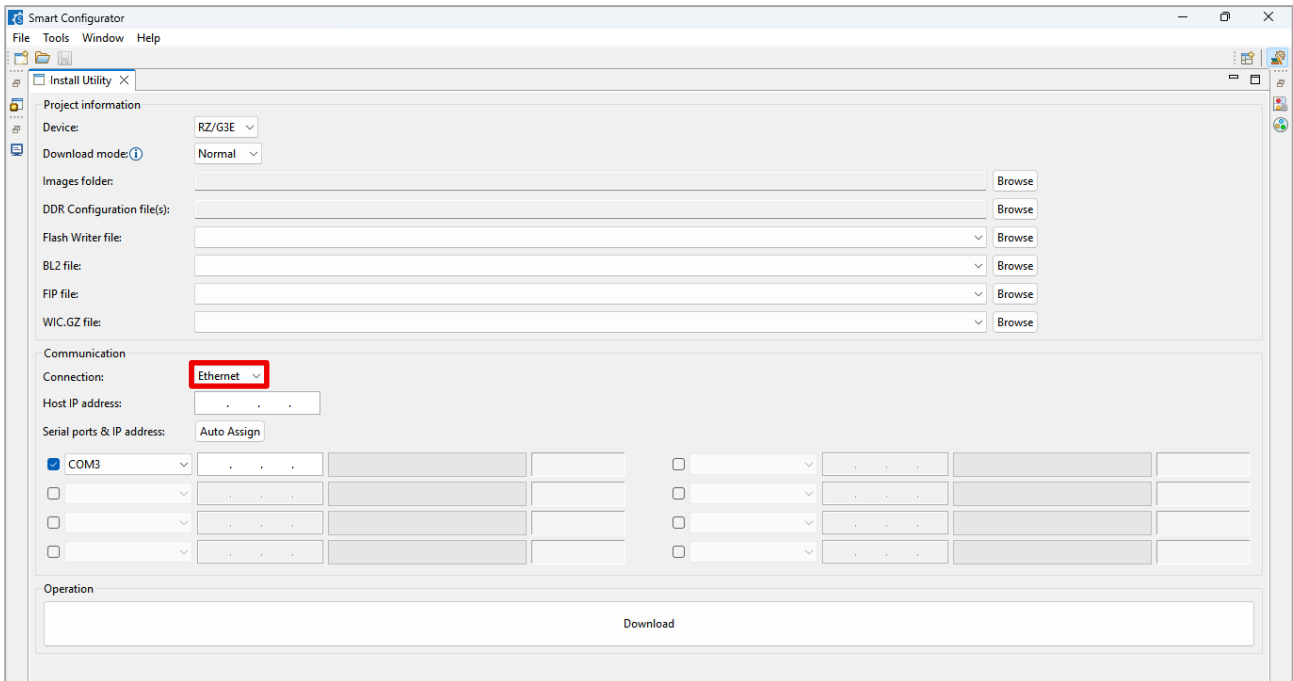
[Target]

- RZ/G3E

3.1.4 Added Ethernet communication support for Install Utility

Smart Configurator for RZ supports an editor to automated fundamental step which flashes bootloader and operation system disk image onto the targeted RZ/G board.

In addition to the existing USB OTG communication interface, Ethernet communication is now supported.



Note:

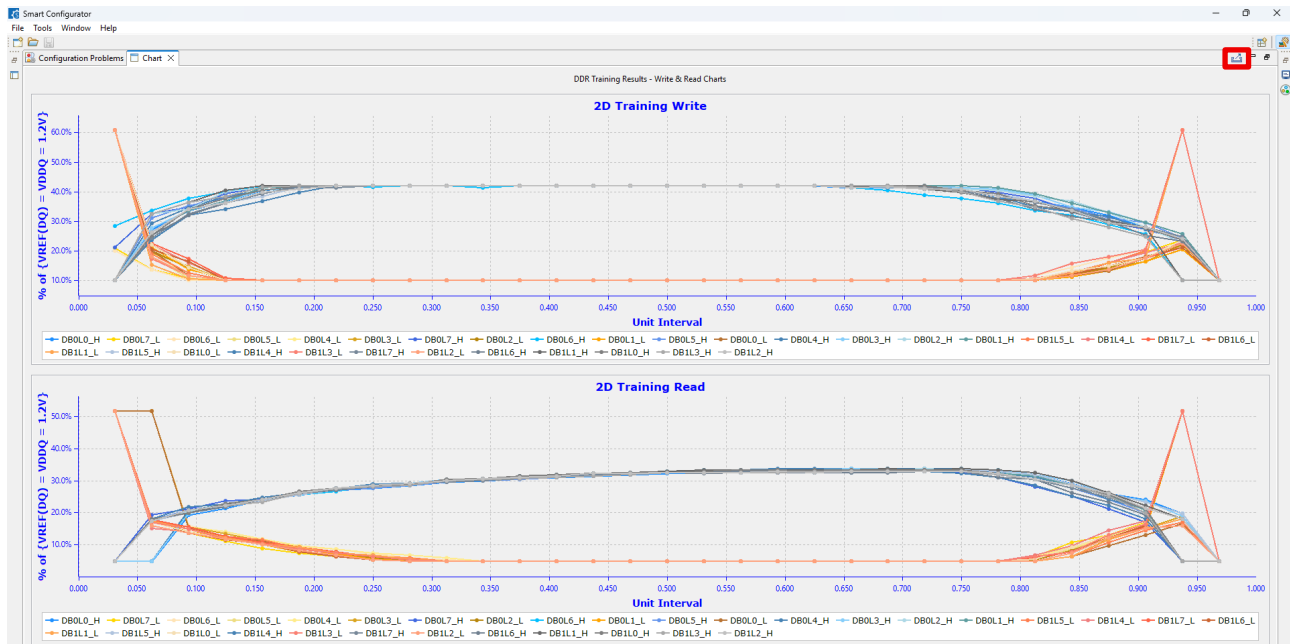
- The RZ/G board must be connected to use this feature.

3.1.5 Added support for WIC image files from VLP Linux v4.0.1 in the Install Utility

The Install Utility now supports WIC image files from VLP Linux v4.0.1.

3.1.6 Added image export functionality for the eye-opening diagram in DDR Tools

The DDR Tools now supports to export the eye-opening diagram as an image.



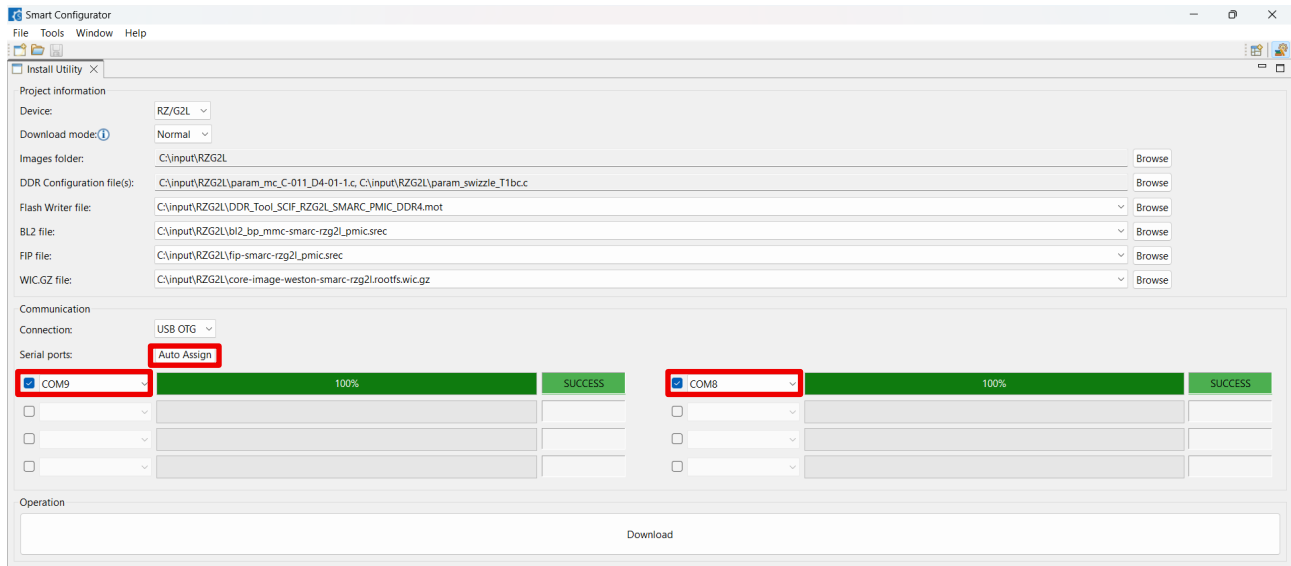
Note: This feature is valid only for RZ/G3x device group.

3.1.7 Added support to configure the DDR pins between Pin page and DDR page

Smart Configurator for RZ now supports the DDR pins configuration between Pin page and DDR page.

3.1.8 Added support to automatically detect virtual COM ports in the Install Utility

The Install Utility now supports automatic detection of the corresponding serial (COM) port when a targeted RZ/G board is connected.



3.2 Correction of issues/limitations

3.2.1 Fixed address range limitation in DDR Tools affecting Stress checker

In the previous version, the allowable address range of the DDR Tool stress checker function is incorrect. If the start address entered falls within [0x40000000 – 0x4000003F], the process will be prohibited. The difference in ranges is as follows:

- Current range: [0x40000040 – 0x13FFFFFF]
- Expected range: [0x40000000 – 0x13FFFFFF]

In the current version, the issue is now corrected.

4. List of [Notes] RENESAS TOOL NEWS

[Notes] Below is a list of notifications delivered by RENESAS TOOL NEWS.

| Issue date | Document No. | Description | Applicable MCUs | Fixed version |
|------------|---------------------------|---------------------------------------------------------------------------------------------------------------------------------|-----------------|---------------|
| 2019/12/16 | R20TS0520 | Incorrect display of peripheral function names "Camera Serial Interface" and "SPI Multi I/O Bus Controller" on pin function tab | RZ/G2E | V1.8.0 |
| 2021/7/16 | R20TS0739 | Missing pins for I2C0, I2C3 and I2C5 of RZ/G2M | RZ/G2M | V1.10.1 |

5. Points for Limitation

There is no limitation for Smart Configurator for RZ V2.1.0.

6. Point for Caution

This chapter describes the cautions for Smart Configurator for RZ V2.1.0.

6.1 List of Caution

| No. | Descriptions | RZ/A1 | RZ/G1 | RZ/G2 | RZ/V2 |
|-----|------------------------------------------------------------------------------------|-------|-------|-------|-------|
| 1 | Functions not supported by RZ/A1 package | ✓ | - | - | - |
| 2 | Projects created using Smart Configurator for RZ V1.3.0 and before | - | ✓ | - | - |

✓ :Applicable, -:Not Applicable

6.2 Details of Caution

6.2.1 Functions not supported by RZ/A1 package

RZ/A1 package does not support code generation and board configuration.

[Target]

RZ/A1H, A1L, A1LC, A1LU, A1M

6.2.2 Projects created using Smart Configurator for RZ V1.3.0 and before

Projects created using Smart Configurator for RZ V1.3.0 and before do not have [Group] information. Please confirm [Group] after opening those projects.

[Workaround]

None.

[Target]

RZ/G1C, G1E, G1H, G1M, G1N

Revision History

| Rev. | Section | Description |
|-------------|----------------|----------------------|
| 1.00 | - | First edition issued |
| | | |

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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